

# MITSUBISHI LSIs

## M5M5165P,FP-70,-10,-12,-15, -70L,-10L,-12L,-15L

65536-BIT (8192-WORD BY 8-BIT) CMOS STATIC RAM

### DESCRIPTION

The M5M5165P, FP is a 65536-bit CMOS static RAM organized as 8192 words by 8 bits which is fabricated using high-performance double polysilicon CMOS technology. The use of resistive load NMOS cells and CMOS periphery result in a high-density and low-power static RAM. It is ideal for the memory systems which require simple interface.

The stand-by current is low enough for a battery back-up application.

### FEATURES

Type	Access time (max)	Power supply current	
		Active (max)	Stand-by (max)
M5M5165P, FP-70	70ns		
M5M5165P, FP-10	100ns		
M5M5165P, FP-12	120ns		
M5M5165P, FP-15	150ns		
M5M5165P, FP-70L	70ns	50mA	2 mA
M5M5165P, FP-10L	100ns		
M5M5165P, FP-12L	120ns		
M5M5165P, FP-15L	150ns		
			20 $\mu$ A (V <sub>CC</sub> =5.5V) 10 $\mu$ A (V <sub>CC</sub> =3.0V)

- Single +5V Power Supply
- Fully Static Operation: No Clocks, No Refresh
- Data-Hold on +2V Power Supply
- Directly TTL Compatible: All Inputs and Outputs
- Three-State Outputs: OR-tie Capability
- Simple Memory Expansion by  $S_1$ ,  $S_2$
- $\overline{OE}$  Prevents Data Contention in The I/O Bus
- Common Data I/O

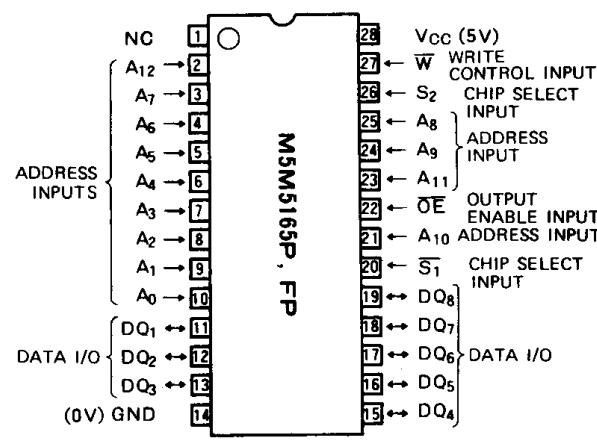
### APPLICATION

Small Capacity Memory Units.

### FUNCTION

The operation mode of the M5M5165P, FP is determined by a combination of the device control inputs  $S_1$ ,  $S_2$ ,  $\overline{W}$

### PIN CONFIGURATION (TOP VIEW)



NC : NO CONNECTION

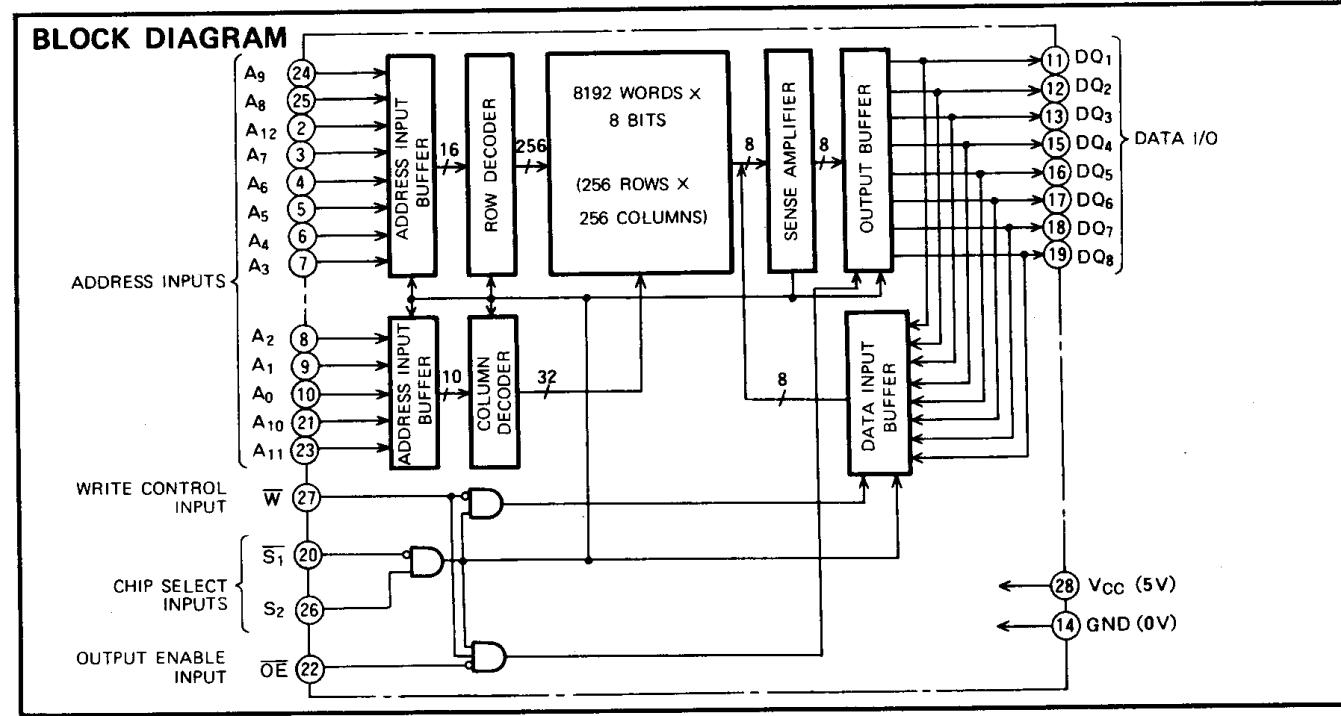
Outline 28P4 (DIP)

28P2W-C (SOP)

and  $\overline{OE}$ . Each mode is summarized in the function table. (see next page)

A write cycle is executed whenever the low level  $\overline{W}$  overlaps with the low level  $\overline{S}_1$  and the high level  $S_2$ . The address must be set up before the write cycle and must be stable during the entire cycle. The data is latched into a cell on the trailing edge of  $\overline{W}$ ,  $S_1$  or  $S_2$ , whichever occurs first, requiring the set-up and hold time relative to these edge to be maintained. The Output enable input  $\overline{OE}$  directly controls the output stage. Setting the  $\overline{OE}$  at a high level, the output stage is in a high-impedance state, and the data bus contention problem in the write cycle is eliminated.

A read cycle is executed by setting  $\overline{W}$  at a high level and  $\overline{OE}$  at a low level while  $S_1$  and  $S_2$  are in an active state ( $S_1=L$ ,



**M5M5165P, FP-70, -10, -12, -15, -70L, -10L, -12L, -15L****65536-BIT (8192-WORD BY 8-BIT) CMOS STATIC RAM****S<sub>2</sub>=H)**

When setting S<sub>1</sub> at a high level or S<sub>2</sub> at a low level, the chip is in a non-selectable mode in which both reading and writing are disabled. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expansion by S<sub>1</sub> and S<sub>2</sub>. The power supply current is reduced as low as the stand-by current which is specified as I<sub>CC3</sub> or I<sub>CC4</sub>, and the memory data can be held at +2V power supply, enabling battery back-up operation during power failure or power-down operation in the non-selected mode.

**FUNCTION TABLE**

S <sub>1</sub>	S <sub>2</sub>	W	OE	Mode	DQ	I <sub>CC</sub>
X	L	X	X	Non selection	high-impedance	Standby
H	X	X	X	Non selection	high-impedance	Standby
L	H	L	X	Write	D <sub>IN</sub>	Active
L	H	H	L	Read	D <sub>OUT</sub>	Active
L	H	H	H		high-impedance	Active

**ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Conditions	Ratings	Unit
V <sub>CC</sub>	Supply voltage	With respect to GND	-0.3~7	V
V <sub>I</sub>	Input voltage		-0.3~V <sub>CC</sub> +0.3	V
V <sub>O</sub>	Output voltage		0~V <sub>CC</sub>	V
P <sub>d</sub>	Power dissipation	T <sub>a</sub> =25°C	700	mW
T <sub>opr</sub>	Operating temperature		0~70	°C
T <sub>stg</sub>	Storage temperature		-65~150	°C

**ELECTRICAL CHARACTERISTICS (T<sub>a</sub>=0~70°C, V<sub>CC</sub>=5V ±10%, unless otherwise noted)**

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V <sub>IH</sub>	High input voltage		2.2		V <sub>CC</sub> +0.3	V
V <sub>IL</sub>	Low input voltage		-0.3		0.8	V
V <sub>OH</sub>	High output voltage	I <sub>OH</sub> =-1mA	2.4			V
V <sub>OL</sub>	Low output voltage	I <sub>OL</sub> =2 mA			0.4	V
I <sub>I</sub>	Input current	V <sub>I</sub> =0~V <sub>CC</sub>			±1	μA
I <sub>OZH</sub>	High level output current in off-state	S <sub>1</sub> =V <sub>IH</sub> or S <sub>2</sub> =V <sub>IL</sub> or OE=V <sub>IH</sub> V <sub>I/O</sub> =0~V <sub>CC</sub>			1	μA
I <sub>OZL</sub>	Low level output current in off-state				-1	μA
I <sub>CC1</sub>	Active supply current	S <sub>2</sub> ≤0.2, S <sub>2</sub> ≥V <sub>CC</sub> -0.2 Outout open Other inputs ≤0.2 or ≥V <sub>CC</sub> -0.2		30	45	mA
I <sub>CC2</sub>	Active supply current	S <sub>1</sub> =V <sub>IL</sub> or S <sub>2</sub> =V <sub>IH</sub> Output open Other inputs =V <sub>IH</sub>		35	50	mA
I <sub>CC3</sub>	Stand-by supply current	(1) S <sub>2</sub> ≤0.2V, Other inputs =0~V <sub>CC</sub> (2) S <sub>1</sub> ≥V <sub>CC</sub> -0.2V, S <sub>2</sub> ≥V <sub>CC</sub> -0.2V, Other inputs=0~V <sub>CC</sub>	P, FP		2	mA
I <sub>CC4</sub>	Stand-by supply current		P, FP-L		20	μA
C <sub>i</sub>	Input capacitance (T <sub>a</sub> =25°C)	V <sub>I</sub> =GND, V <sub>i</sub> =25mVrms, f=1MHz			3	mA
C <sub>o</sub>	Output capacitance (T <sub>a</sub> =25°C)	V <sub>O</sub> =GND, V <sub>o</sub> =25mVrms, f=1MHz			6	pF
					8	pF

Note 1 Direction for current flowing into IC is indicated as positive (no mark)

2 Typical value is V<sub>CC</sub>=5V, T<sub>a</sub>=25°C

**M5M5165P,FP-70, -10, -12, -15, -70L, -10L, -12L, -15L****65536-BIT (8192-WORD BY 8-BIT) CMOS STATIC RAM**SWITCHING CHARACTERISTICS ( $T_a = 0 \sim 70^\circ C$ ,  $V_{CC} = 5V \pm 10\%$ , unless otherwise noted)

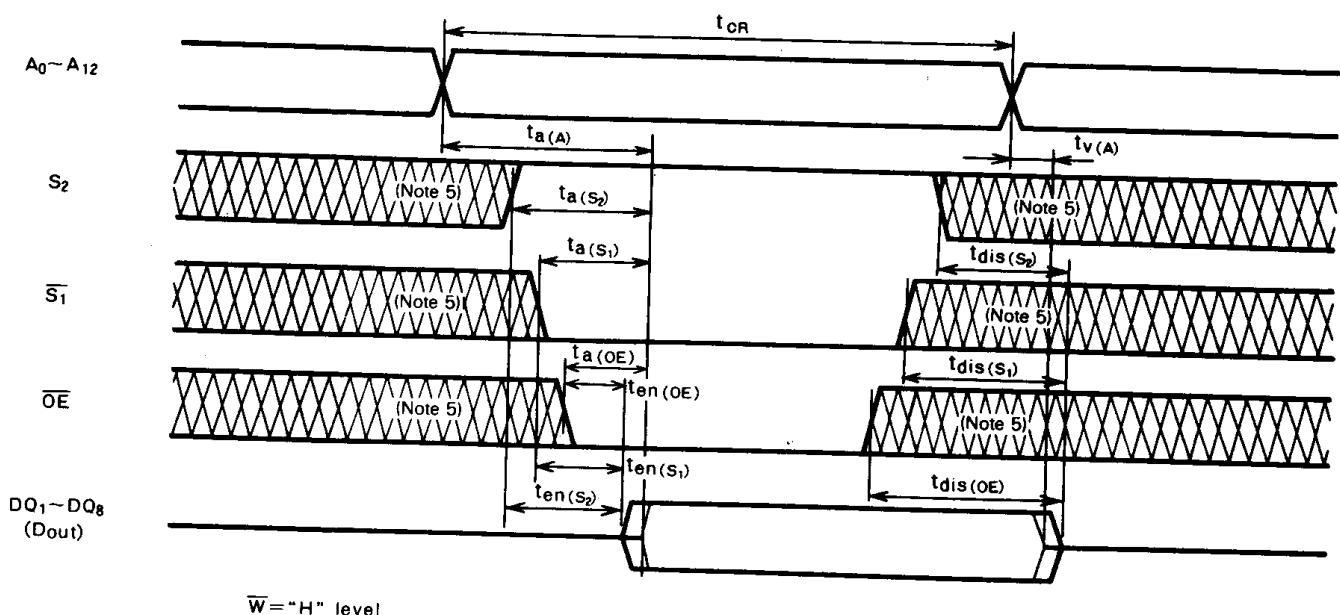
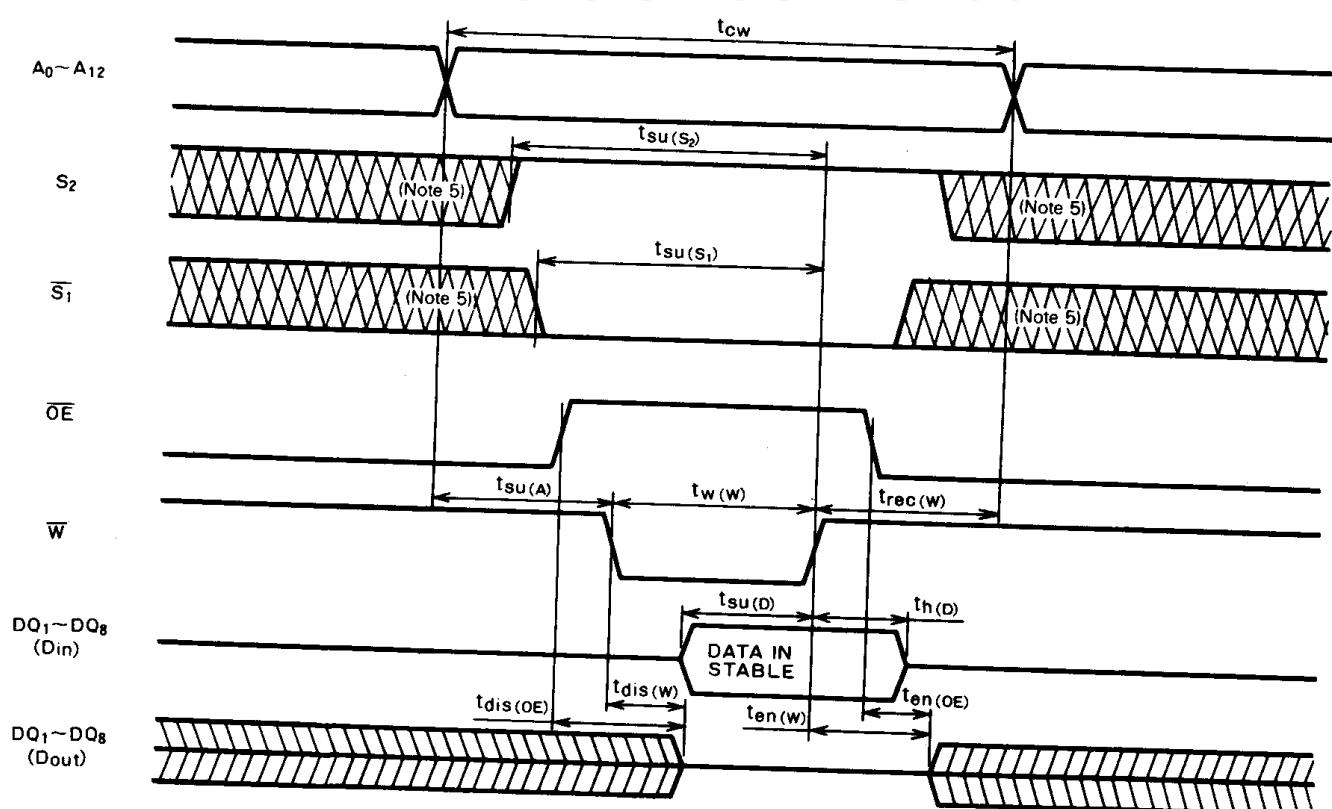
## Read cycle

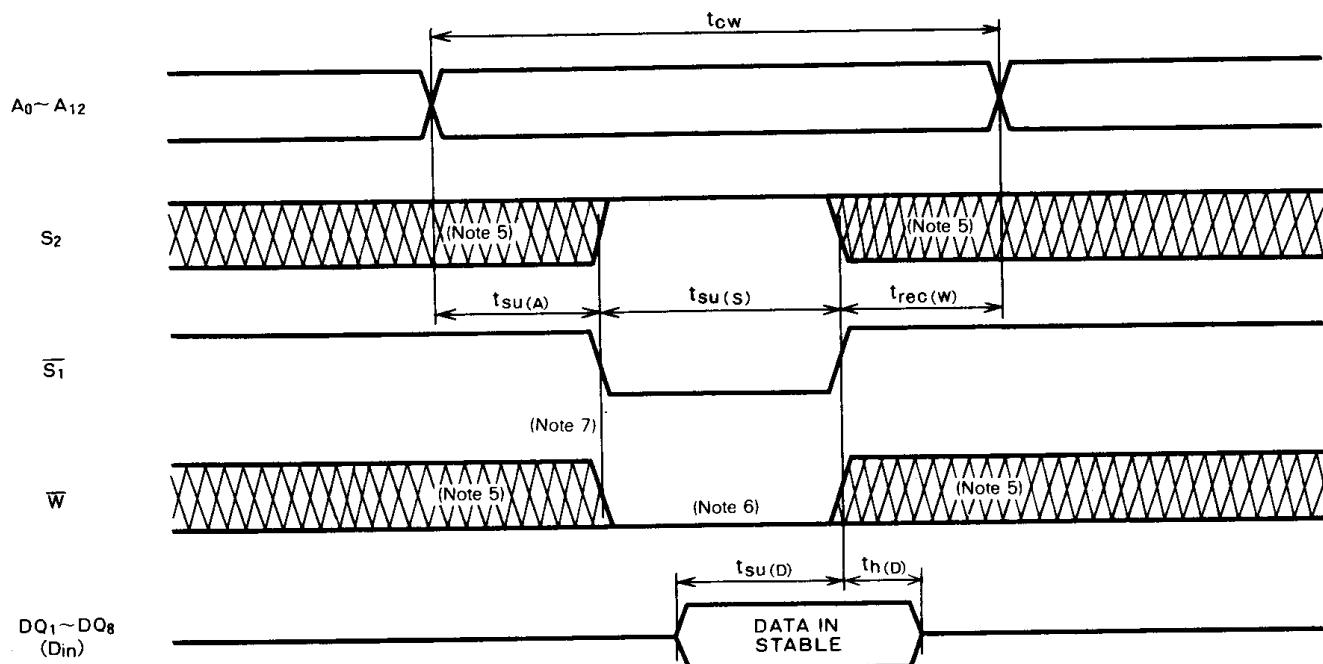
Symbol	Parameter	Limits												Unit	
		M5M5165P,FP-70 M5M5165P,FP-70L			M5M5165P,FP-10 M5M5165P,FP-10L			M5M5165P,FP-12 M5M5165P,FP-12L			M5M5165P,FP-15 M5M5165P,FP-15L				
		Min	Typ	Max											
$t_{CR}$	Read cycle time	70			100			120			150			ns	
$t_a(A)$	Address access time			70			100			120			150	ns	
$t_a(S_1)$	Chip select 1 access time			70			100			120			150	ns	
$t_a(S_2)$	Chip select 2 access time			70			100			120			150	ns	
$t_a(OE)$	Output enable access time			35			50			60			70	ns	
$t_{dis}(S_1)$	Output disable time after $S_1$ high			30			35			40			50	ns	
$t_{dis}(S_2)$	Output disable time after $S_2$ low			30			35			40			50	ns	
$t_{dis}(OE)$	Output disable time after $\overline{OE}$ high			30			35			40			50	ns	
$t_{en}(S_1)$	Output enable time after $S_1$ low	5			10			10			10			ns	
$t_{en}(S_2)$	Output enable time after $S_2$ high	5			10			10			10			ns	
$t_{en}(OE)$	Output enable time after $\overline{OE}$ low	5			10			10			10			ns	
$t_v(A)$	Data valid time after address change	20			20			20			20			ns	

TIMING REQUIREMENTS ( $T_a = 0 \sim 70^\circ C$ ,  $V_{CC} = 5V \pm 10\%$ , unless otherwise noted)

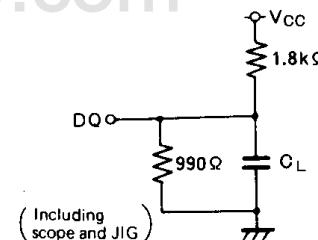
## Write cycle

Symbol	Parameter	Limits												Unit	
		M5M5165P,FP-70 M5M5165P,FP-70L			M5M5165P,FP-10 M5M5165P,FP-10L			M5M5165P,FP-12 M5M5165P,FP-12L			M5M5165P,FP-15 M5M5165P,FP-15L				
		Min	Typ	Max											
$t_{cw}$	Write cycle time	70			100			120			150			ns	
$t_w(w)$	Write pulse width	40			60			70			90			ns	
$t_{su}(A)$	Address set up time	0			0			0			0			ns	
$t_{su}(S)$	Chip select set up time	65			80			85			100			ns	
$t_{su}(D)$	Data set up time	30			35			40			50			ns	
$t_h(D)$	Data hold time	5			5			5			5			ns	
$t_{rec}(w)$	Write recovery time	5			5			10			10			ns	
$t_{dis}(w)$	Output disable time after $\overline{W}$ low	0	30			35			40			50		ns	
$t_{dis}(OE)$	Output disable time after $\overline{OE}$ high	0	30			35			40			50		ns	
$t_{en}(w)$	Output enable time after $\overline{W}$ high	5			10			10			10			ns	
$t_{en}(OE)$	Output enable time after $\overline{OE}$ low	5			10			10			10			ns	

**M5M5165P, FP-70, -10, -12, -15, -70L, -10L, -12L, -15L****65536-BIT (8192-WORD BY 8-BIT) CMOS STATIC RAM****TIMING DIAGRAM****Read cycle****Write cycle ( $\overline{W}$  control)**

**M5M5165P, FP-70, -10, -12, -15, -70L, -10L, -12L, -15L****65536-BIT (8192-WORD BY 8-BIT) CMOS STATIC RAM****Write cycle (S control)****Note 4: Test condition**Input pulse level . . . . V<sub>IH</sub> = 2.4V, V<sub>IL</sub> = 0.6V

Input rise and fall time . . . . 10ns

Reference level . . . . V<sub>OH</sub> = V<sub>OL</sub> = 1.5VTransition is measured  $\pm 500\text{mV}$  from  
steady state voltage. (for t<sub>en</sub>, t<sub>dis</sub>)Output loads . . . . Fig. 1, C<sub>L</sub> = 100pF (P, FP-10, -12, -15, -10L, -12L, -15L)C<sub>L</sub> = 30pF (P, FP-70, -70L)C<sub>L</sub> = 5pF (for t<sub>en</sub>, t<sub>dis</sub>)**Fig. 1 Output load**

Note 5: Hatching indicates the state is don't care.

6: Writing is executed while S<sub>2</sub> high overlaps S<sub>1</sub> and W low.7: If W goes low simultaneously with or prior to S<sub>1</sub> low or S<sub>2</sub> high, the output remains in the high-impedance state.

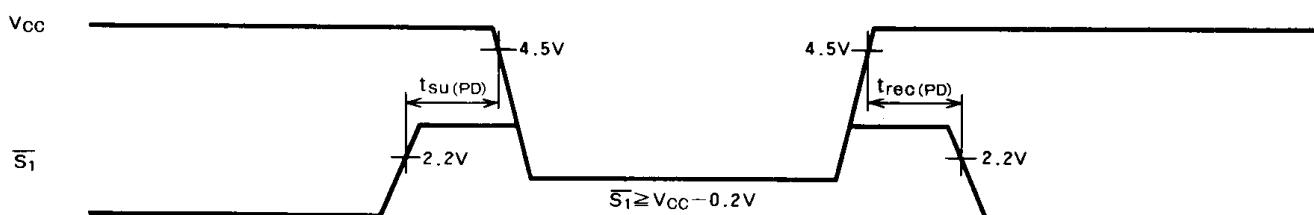
8: Don't apply inverted phase signal externally when DQ pin is in output mode.

**M5M5165P, FP-70, -10, -12, -15, -70L, -10L, -12L, -15L****65536-BIT (8192-WORD BY 8-BIT) CMOS STATIC RAM****POWER DOWN CHARACTERISTICS****ELECTRICAL CHARACTERISTICS** ( $T_a = 0 \sim 70^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V <sub>CC(PD)</sub>	Power down supply voltage		2			V
V <sub>I(S<sub>1</sub>)</sub>	Chip select input S <sub>1</sub>	2.2V ≤ V <sub>CC(PD)</sub>	2.2			V
		2V ≤ V <sub>CC(PD)</sub> ≤ 2.2V		V <sub>CC(PD)</sub>		
V <sub>I(S<sub>2</sub>)</sub>	Chip select input S <sub>2</sub>	4.5V ≤ V <sub>CC(PD)</sub>			0.8	V
		V <sub>CC(PD)</sub> < 4.5V			0.2	
I <sub>CC(PD)</sub>	Power down supply current	V <sub>CC</sub> =3V, Other inputs = 3V	P, FP		2	mA
			P, FP-L		10 *	μA

Note 3: When S<sub>1</sub> is operated at 2.2V (V<sub>IH</sub> min) and the supply voltage is between 4.5V and 2.4V, supply current is defined as I<sub>CC4</sub>.\*: I<sub>CC(PD)</sub> = 1 μA at T<sub>a</sub> = 25°C**TIMING REQUIREMENTS** ( $T_a = 0 \sim 70^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
t <sub>su (PD)</sub>	Power down setup time		0			ns
t <sub>rec (PD)</sub>	Power down recovery time		t <sub>CR</sub>			ns

**POWER DOWN CHARACTERISTICS**  
**S<sub>1</sub> control****S<sub>2</sub> control**